

Matched N & P R_{DS(ON)}—Minimizes Power Losses

Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2) Halogen and Antimony Free. "Green" Device (Note 3) Qualified to AEC-Q101 Standards for High Reliability The DMC4050SSDQ is suitable for automotive applications requiring specific change control; this part is AEC-Q101 qualified, PPAP capable, and manufactured in IATF 16949

https://www.diodes.com/guality/product-definitions/

Case Material: Molded Plastic, "Green" Molding Compound.

Terminals: Finish—Matte Tin Annealed over Copper Leadframe.

Fast Switching-Minimizes Switching Losses

Dual Device—Reduces PCB Area

Features and Benefits

certified facilities.

Mechanical Data

Case: SO-8

G1

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Product Summary

		I _D	
Device	BV _{DSS}	R _{DS(ON)} Max	T _A = +25°C
			(Notes 7 & 9)
Q1	40V	45mΩ @ V _{GS} = 10V	5.8A
QI	Q1 40V	60mΩ @ V _{GS} = 4.5V	4.2A
Q2	40\/	45mΩ @ V _{GS} = -10V	-5.8A
QZ	-40V	60mΩ @ V _{GS} = -4.5V	-4.2A

Description and Applications

This MOSFET is designed to meet the stringent requirements of Automotive applications. It is qualified to AEC-Q101, supported by a PPAP and is ideal for use in:

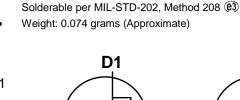
SO-8

- 3-Phase BLDC Motor
- CCFL Backlighting



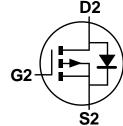
Top View

Top View



S1

UL Flammability Classification Rating 94V-0 Moisture Sensitivity: Level 1 per J-STD-020



Equivalent Circuit

Ordering Information (Note 4)

Part Number	Case	Packaging
DMC4050SSDQ-13	SO-8	2500/Tape & Reel

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and

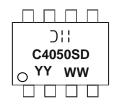
Lead-free.

Notes:

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



Dill = Manufacturer's Marking
C4050SD = Product Type Marking Code
YYWW = Date Code Marking
YY or YY = Year (ex: 20 = 2020)
WW = Week (01 - 53)



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	N-Channel - Q1	P-Channel - Q2	Units
Drain-Source Voltage			V _{DSS}	40	-40	V
Gate-Source Voltage			V _{GSS}	±20	±20	v
		(Notes 6 & 8)		5.8	-5.8	
Continuous Drain Current	$V_{GS} = 10V$	T _A = +70°C (Notes 6 & 8)	ID	4.38	-4.52	
		(Notes 5 & 8)		4.2	-4.2	
		(Notes 5 & 9)		5.3	-5.3	А
Pulsed Drain Current V _{GS} = 10V		(Notes 7 & 8)	I _{DM}	24.1	-24.9	
Continuous Source Current (Body Diode)		(Notes 6 & 8)	Is	2.5	-2.5	
Pulsed Source Current (Body Diode)		(Notes 7 & 8)	I _{SM}	24.1	-24.9	

Thermal Characteristics

Characteristic	Symbol	Value	Unit		
Devues Dissinction	(Notes 5 & 8)		1.25		
Power Dissipation	(Notes 5 & 9)	PD	1.8	W	
	(Notes 6 & 8)		2.14		
	(Notes 5 & 8)		100		
Thermal Resistance, Junction to Ambient	(Notes 5 & 9)	R _{OJA}	70	00.00/	
Ī	(Notes 6 & 8)		58	°C/W	
Thermal Resistance, Junction to Lead	(Notes 5 & 10)	R _{ƏJL}	51		
Operating and Storage Temperature Range		T _{J,} T _{STG}	-55 to +150	°C	

5. For a device surface mounted on 25mm × 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition. Notes:

6. Same as Note 5, except the device is measured at t \leq 10 sec. 7. Same as Note 5, except the device is pulsed with D = 0.02 and pulse width 300µs.

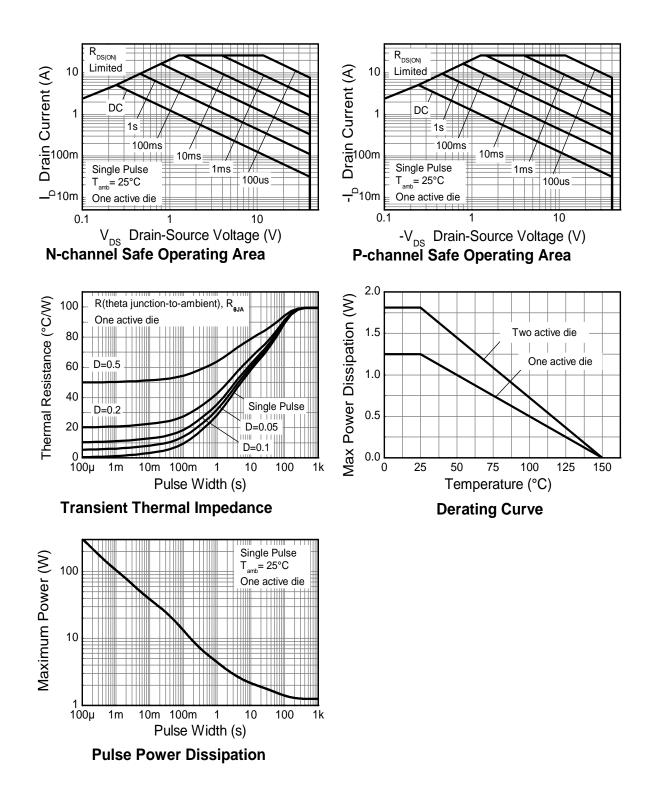
8. For a dual device with one active die.

9. For a device with two active die running at equal power.

10. Thermal resistance from junction to solder-point (at the end of the drain lead).



Thermal Characteristics (continued)





Electrical Characteristics (Q1 N-Channel) (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 11)	Symbol	IVIIII	тур	WIAA	Unit	Test condition	
Drain-Source Breakdown Voltage	BV _{DSS}	40	_	_	V	$V_{GS} = 0V, I_D = 250 \mu A$	
Zero Gate Voltage Drain Current $T_J = +25^{\circ}C$	I _{DSS}	_	—	1.0	μA	$V_{DS} = 40V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}		—	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 11)							
Gate Threshold Voltage	V _{GS(TH)}	0.8	1.3	1.8	V	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$	
Static Drain-Source On-Resistance			20	45	mΩ	$V_{GS} = 10V, I_D = 3A$	
	R _{DS(ON)}		33	60		$V_{GS} = 4.5 V, I_D = 3 A$	
Forward Transfer Admittance	Y _{FS}	_	12.6	_	S	$V_{DS} = 5V, I_D = 3A$	
Diode Forward Voltage (Note 11)	V _{SD}	_	0.7	1.0	V	$V_{GS} = 0V, I_S = 1A$	
DYNAMIC CHARACTERISTICS (Note 12)							
Input Capacitance	CISS		1,790.8		pF		
Output Capacitance	C _{OSS}		160.6		pF	V _{DS} = 20V, V _{GS} = 0V, f = 1.0MHz	
Reverse Transfer Capacitance	C _{RSS}	_	120.5	_	pF	1 - 1.00012	
Gate Resistance	R _G	_	1.03		Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge	Q_{G}		37.56		nC	V 10V V 20V	
Gate-Source Charge	Q _{GS}	_	7.8		nC	V _{GS} = 10V, V _{DS} = 20V, I _D = 3A	
Gate-Drain Charge	Q _{GD}		6.6		nC		
Turn-On Delay Time	t _{D(ON)}		8.08		ns		
Turn-On Rise Time	t _R		15.14		ns	$V_{GS} = 10V, V_{DS} = 20V,$	
Turn-Off Delay Time	t _{D(OFF)}		24.29		ns	$I_D = 3A$	
Turn-Off Fall Time	tF		5.27		ns		

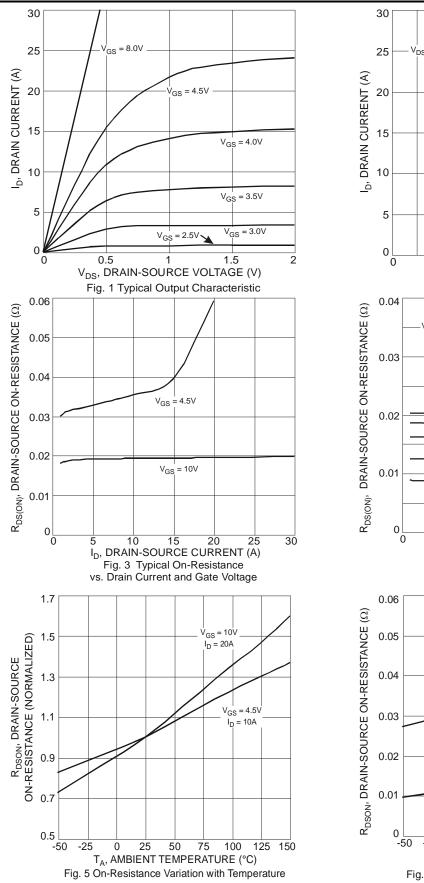
Electrical Characteristics (Q2 P-Channel) (@T_A = +25°C, unless otherwise specified.)

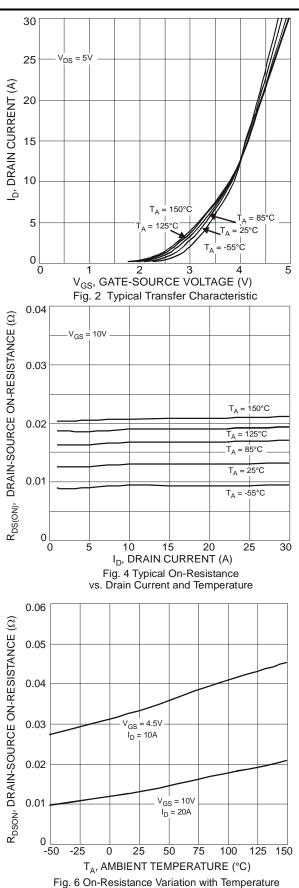
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Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 11)						-	
Drain-Source Breakdown Voltage	BV _{DSS}	-40	—	_	V	$V_{GS} = 0V, I_D = -250 \mu A$	
Zero Gate Voltage Drain Current T _J = +25°C	IDSS			-1.0	μA	$V_{DS} = -40V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}	_	—	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 11)							
Gate Threshold Voltage	V _{GS(TH)}	-0.8	-1.3	-1.8	V	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	
Static Drain-Source On-Resistance			28	45	mΩ	$V_{GS} = -10V, I_D = -3A$	
	R _{DS(ON)}	_	30	60	11152	$V_{GS} = -4.5V, I_D = -3A$	
Forward Transfer Admittance	Y _{FS}	_	16.6	_	S	$V_{DS} = -5V, I_D = -3A$	
Diode Forward Voltage (Note 11)	V _{SD}	_	-0.7	-1.0	V	$V_{GS} = 0V, I_{S} = -1A$	
DYNAMIC CHARACTERISTICS (Note 12)							
Input Capacitance	CISS	_	1,643.17		pF		
Output Capacitance	Coss	_	179.13		pF	$V_{DS} = -20V, V_{GS} = 0V,$ - f = 1.0MHz	
Reverse Transfer Capacitance	C _{RSS}	_	127.82		pF	1 - 1.00012	
Gate Resistance	R _G	_	6.43		Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1MHz$	
Total Gate Charge	Q _G		33.66	_	nC	N 40V/ N 00V/	
Gate-Source Charge	Q _{GS}	-	5.54	_	nC	$-V_{GS} = -10V, V_{DS} = -20V,$ $-I_{D} = -3A$	
Gate-Drain Charge	Q _{GD}	-	7.30	_	nC		
Turn-On Delay Time	t _{D(ON)}	—	6.85		ns		
Turn-On Rise Time	t _R	_	14.72	_	ns	$V_{GS} = -10V, V_{DS} = -20V,$	
Turn-Off Delay Time	t _{D(OFF)}	—	53.65		ns	I _D = -3A	
Turn-Off Fall Time	t _F	_	30.86		ns	7	

 Short duration pulse test used to minimize self-heating effect.
 Guaranteed by design. Not subject to production testing. Notes:



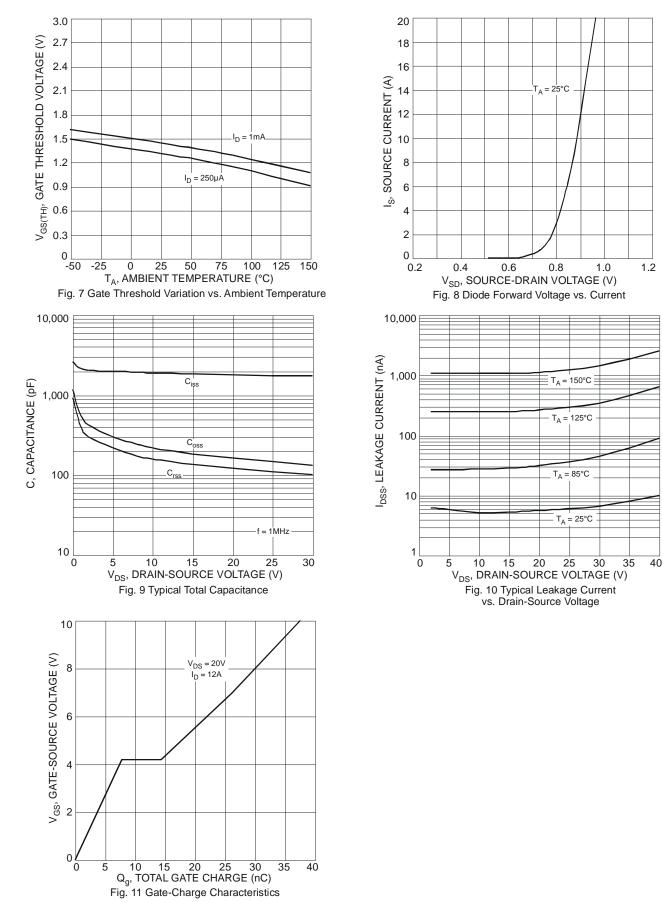
Typical Characteristics (Q1 N-Channel)





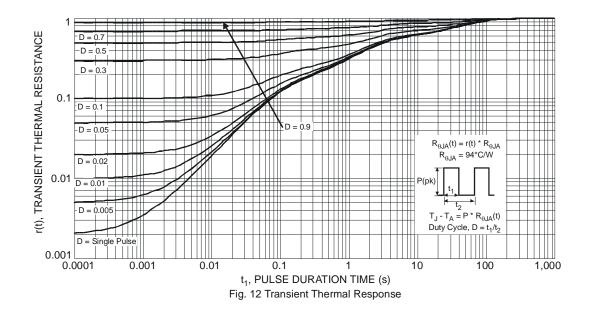
DMC4050SSDQ Document number: DS38781 Rev. 3 - 2





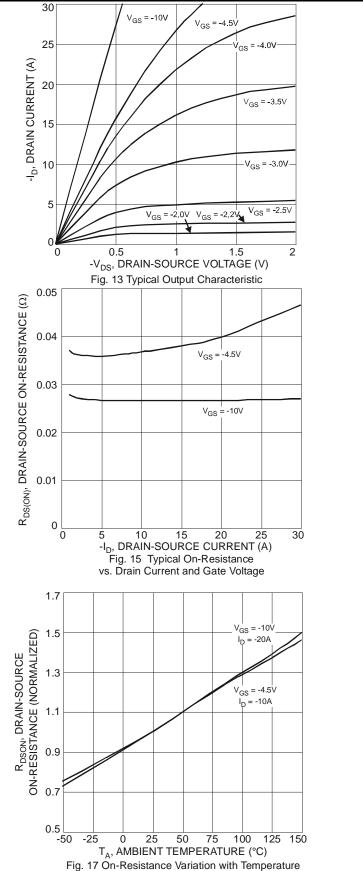


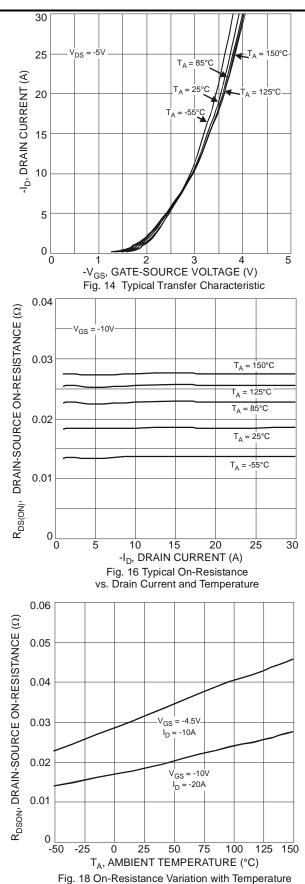






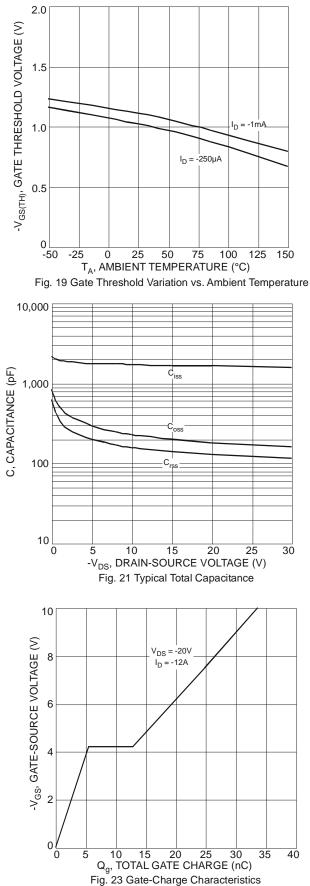
Typical Characteristics (Q2 P-Channel)

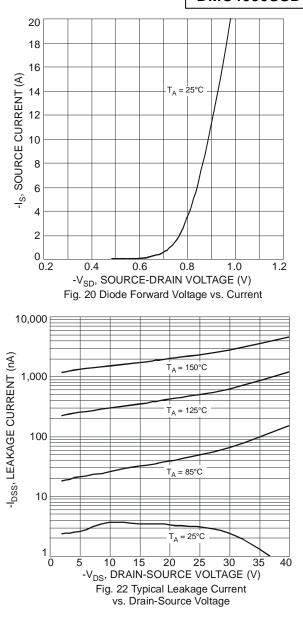




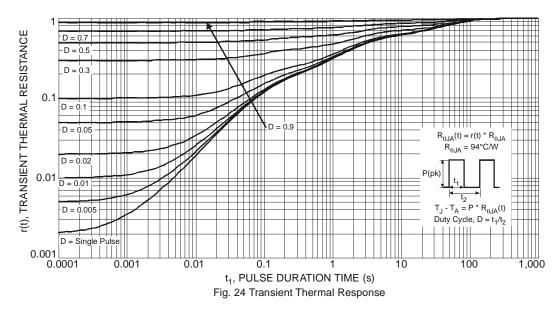








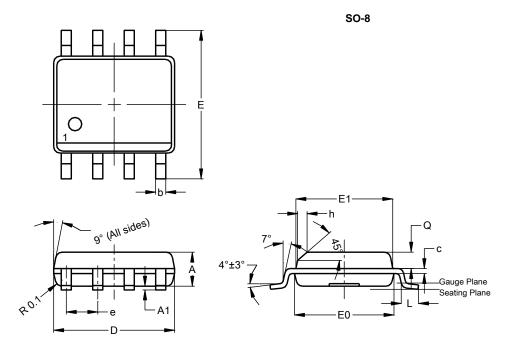






Package Outline Dimensions

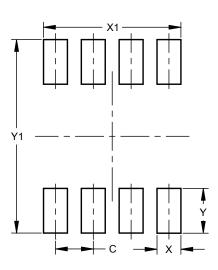
Please see http://www.diodes.com/package-outlines.html for the latest version.



SO-8						
Dim	Min Max Typ					
Α	1.40	1.50	1.45			
A1	0.10	0.20	0.15			
b	0.30	0.50	0.40			
c	0.15	0.25	0.20			
D	4.85	4.95	4.90			
ш	5.90	6.10	6.00			
E1	3.80	3.90	3.85			
E0	3.85	3.95	3.90			
e			1.27			
h	-		0.35			
L	0.62	0.82	0.72			
q	0.60	0.70	0.65			
All	All Dimensions in mm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



SO-8

Dimensions	Value (in mm)
С	1.27
Х	0.802
X1	4.612
Y	1.505
Y1	6.50



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